



5245 Hellyer Avenue
 San Jose, CA 95138
 U.S.A.
 (408) 414-9200

Control No. PCN-19091

March 19, 2019

PRODUCT/PROCESS CHANGE NOTIFICATION

TYPE OF CHANGE: Design Manufacturing Other

This notification is provided in accordance with Power Integrations policy of product/process change notification. If you have any questions or need further assistance, please contact your regional Power Integrations sales office.

DESCRIPTION OF CHANGE

Power Integrations is adding Lapis Kagoshima, Japan factory for the fabricating of the products listed in this notification. There is no change in the manufacturing process or final test program.

REASON FOR CHANGE

Addition of an alternative production line for increased manufacturing capacity and flexibility.

PRODUCTS AFFECTED

Product Family	Part Numbers	Package
LinkSwitch-3	LNK6404D, LNK6407D, LNK6417D, LNK6424D, LNK6427D, SC1142D0, SC1142D00073, SC1142D00193, SC1142D1, SC1142D10077, SC1142D2, SC1142D3, SC1161D0, SC1161D1, SC1161D2, SC1161DZ, SC1170D4	SO-8C
	LNK6407K, LNK6417K, LNK6427K, SC1161K0, SC1161K1, SC1161K2, SC1161KZ, SC1162K0, SC1162K1, SC1162K10216, SC1162K2, SC1162KZ	eSOP-12B

QUALIFICATION STATUS

Refer to Appendix 1 for the qualification data.

EFFECT ON CUSTOMER

No adverse impact is expected in manufacturers' applications. The product will meet the datasheet limits.

EFFECTIVE DATE

June 19, 2019. This date is subject to change. Products assembled at the current wafer fab site will continue to be shipped after implementation of the above change.

SAMPLE AVAILABILITY

Samples will be available 12 weeks from the date of request. Please send requests for samples within two weeks after receipt of this notification to the local Power Integrations sales office.

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Appendix 1
Reliability Engineering
Qualification Report

Qualification Project: E184505

Project Title: **LinkSwitch-3 Product Family Lapis Kagoshima Wafer Fab Transfer Qual Report**

Summary:

Lapis Kagoshima wafer fab was previously qualified for wafer fabrication with the same process technology used by LinkSwitch-3 family of products. One SC1162K2 lot was subjected to a full suite of reliability stress tests to qualify all LinkSwitch-3 products at Lapis Kagoshima. All tests were completed with passing results. Yield and temperature characterization were completed with acceptable results

Based on these results, Lapis Kagoshima is qualified for wafer fabrication of all LinkSwitch-3 products.

Reliability Test Descriptions and Conditions

Test Name	Conditions	Reference Specification
DOPL (Dynamic Operating Life Test)	Ta = 95°C (Tj = 125°C,), Vd(Peak) = 580V	EIA/JESD22-A108
HALT (Humidity Accelerated Life Test)	DOPL at Ta = 85°C, 85% RH, Tj=115°C	Internal Specification
HTRB (High Temp Reverse Bias Test)	Ta=150°C; off-state bias, Vd = 580V	EIA/JESD22-A108
THBT (Temperature Humidity Bias Test)	85°C, 85% RH; off-state bias, Vd = 30V	EIA/JESD22-A101
TMCL (Temperature Cycle)	-40°C to +125°C, air-to=air	EIA/JESD22-A104
High Temperature Storage Life (HTSL)	Ta=150°C; unbiased	EIA/JESD22-A103
MSL1 Preconditioning	24-hr 150C bake → 192-hr 30°C, 60% RH soak → 3 passes 260C solder reflow	IPC/JEDEC J-STD-020

Dynamic Operating Life Test (DOPL)

Device	Assy Lot	Wafer Lot	Package/Assy Site	Total Hours	Results (Rej/SS)
SC1162K2	7T279A	DM178C4 Lot ADC190-001J	eSOP-12B / UTL	MSL1 +1000	0 / 47

High Temperature Reverse Bias (HTRB)

Device	Assy Lot	Wafer Lot	Package/Assy Site	Total Hours	Results (Rej/SS)
SC1162K2	7T279A	DM178C4 Lot ADC190-001J	eSOP-12B / UTL	MSL1 +1000	0 / 47

Humidity Accelerated Life Test (HALT)

Device	Assy Lot	Wafer Lot	Package/Assy Site	Total Hours	Results (Rej/SS)
SC1162K2	7T279A	DM178C4 Lot ADC190-001J	eSOP-12B / UTL	MSL1 +1000	0 / 20

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Temperature / Humidity Bias (THBT)

Device	Assy Lot	Wafer Lot	Package/Assy Site	Total Hours	Results (Rej/SS)
SC1162K2	7T279A	DM178C4 Lot ADC190-001J	eSOP-12B / UTL	MSL1 +1000	0 / 47

Temperature Cycling (TMCL)

Device	Assy Lot	Wafer Lot	Package/Assy Site	Total Cycles	Results (Rej/SS)
SC1162K2	7T279A	DM178C4 Lot ADC190-001J	eSOP-12B / UTL	MSL1 +1700	0 / 47

High Temperature Storage Life (HTSL)

Device	Assy Lot	Wafer Lot	Package/Assy Site	Total Hours	Results (Rej/SS)
SC1162K2	7T279A	DM178C4 Lot ADC190-001J	eSOP-12B / UTL	MSL1 +1000	0 / 47

Conclusion: Based on passing qualification results, Lapis Kagoshima is qualified for wafer fabrication of all LinkSwitch-3 products.

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CUSTOMER ACKNOWLEDGEMENT

Power Integrations requests you acknowledge the receipt of the above-mentioned PCN. If no acknowledgment is received within 30 days of this notification, Power Integrations will assume the change is acceptable. Lack of any additional response within 90 days of this notification further constitutes acceptance of the change.

Power Integrations reserves the right to ship either version manufactured after the effective date.

If you have any questions or need further assistance, please contact your regional Power Integrations sales office. Otherwise, please check the box below, acknowledging the receipt of the PCN.

The indicated Product/Process Change Notification was received by the undersigned authority.

Name/Title: _____

Signature: _____ Date: _____

Email Address/Phone#: _____

Company/Location: _____

CUSTOMER COMMENTS

Please email this signed form to pcn@power.com specifying the PCN# in the subject.

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